

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (original): A support element for a semiconductor package, the support element comprising:

- (a) a first surface having a plurality of conductors;
- (b) a second surface having a plurality of die attach areas, wherein at least one of the die attach areas comprises a defective die attach area;
- (c) the die attach areas including wire bond slots extending from the first surface to the second surface of the support element so as to form openings therethrough; and
- (d) a cover member attached to the at least one defective die attach area so as to cover at least a portion of the wire bond slot, wherein the cover member does not comprise a functional die.

Claim 2 (original): The support element of claim 1, wherein the cover member comprises self-adhesive tape.

Claim 3 (original): The support element of claim 1, wherein the cover member comprises a defective die.

Claim 4 (original): The support element of claim 1, wherein the cover member covers from about 80% to about 90% of the wire bond slot.

Claim 5 (original): The support element of claim 1, wherein the cover member covers at least 70% of an opening formed by the wire bond slot.

Claims 6-18 (canceled).

Claim 19 (original): A support element for a semiconductor package, the support element comprising:

- (a) a first surface having a plurality of conductors;
- (b) a second surface having a plurality of die attach areas, wherein at least one of the die attach areas comprises a defective die attach area;
- (c) the die attach areas including wire bond slots extending from the first surface to the second surface of the support element so as to form openings therethrough; and
- (d) a cover member attached to the at least one defective die attach area so as to cover enough of the opening formed by the wire bond slot so as to substantially eliminate bleeding when the support element is encapsulated, wherein the cover member does not comprise a functional die.

Claim 20 (original): The support element of claim 19, wherein the cover element does not cover enough of the opening so as to cause a negative pressure zone at the wire bond slot when the support element is encapsulated with a liquid plastic.

Claims 21-23 (canceled).

Claim 24 (original): A support element for a semiconductor package, the support element comprising:

- (a) a first surface having a plurality of conductors;
- (b) a second surface having a plurality of die attach areas, wherein at least one of the die attach areas comprises a defective die attach area;
- (c) the die attach areas including wire bond slots extending from the first surface to the second surface of the support element so as to form openings therethrough; and
- (d) a defective die attached to the at least one defective die attach area so as to cover at least a portion of the wire bond slot.

Claim 25 (currently amended): The support element of claim ~~[[24]]~~ 19, wherein the cover member comprises heat-sensitive tape covering a majority of an opening formed by a wire bond slot.

Claim 26 (currently amended): The support element of claim 24, wherein the ~~cover member comprises~~ a defective die ~~covering~~ covers from about 80% to about 90% of an opening formed by a wire bond slot.

Claim 27 (original): A support element for a semiconductor package, the support element comprising:

- (a) a first surface having a plurality of conductors;
- (b) a second surface having a plurality of die attach areas, wherein at least one of the die attach areas comprises a defective die attach area;
- (c) the die attach areas including wire bond slots extending from the first surface to the second surface of the support element so as to form openings therethrough; and
- (d) tape attached to the at least one defective die attach area so as to cover at least a portion of the wire bond slot.

Claim 28 (original): A substrate of a support element, the substrate comprising:

- (a) a first surface having a pattern of conductors;
- (b) a second surface having a die attach area with defective electrical circuitry;
- (c) a wire bond slot forming an opening through the substrate extending from the first surface to the second surface; and
- (d) a defective die attached to the substrate on the second surface so as to cover at least a portion of the wire bond slot.

Claim 29 (original): A support element for a semiconductor package, the support element comprising:

- (a) a first surface having a plurality of conductors;
 - (b) a second surface having a plurality of die attach sites, wherein a first die attach site is defective and a second die attach site is functional;
 - (c) a plurality of integrally connected substrates formed by the first and second surfaces;
- and

(d) the substrate including wire bond slots extending from the first surface to the second surface of the support element so as to form openings therethrough, wherein there is at least one opening formed at the first and the second die attach sites;

(e) a cover member attached to the first die attach site so as to cover from about 70% to about 100% of the opening.

Claims 30-35 (canceled).